



STPOWER StudioOverview

Introduction



A powerful simulation software helps developers select the most suitable device to fit complex and extensive application mission profiles

Provides comprehensive power and thermal analysis that eliminates long, complex, and expensive application testing

Returns accurate estimations of power loss and junction and case temperatures, along with data on nontestable parameters and support for heatsink sizing

Now integrated in the eDesignSuite platform and ready to deliver extensive analyses with a single click





Overview

Dynamic electro-thermal simulation software dedicated to STPOWER devices, now online on eDesignSuite



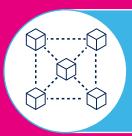
Features:

- Available online on ST eDesignSuite platform
- Supports SLLIMM & ACEPACK families
- Enables DC/AC 3-phase 2-level applications
- Desktop and mobile version



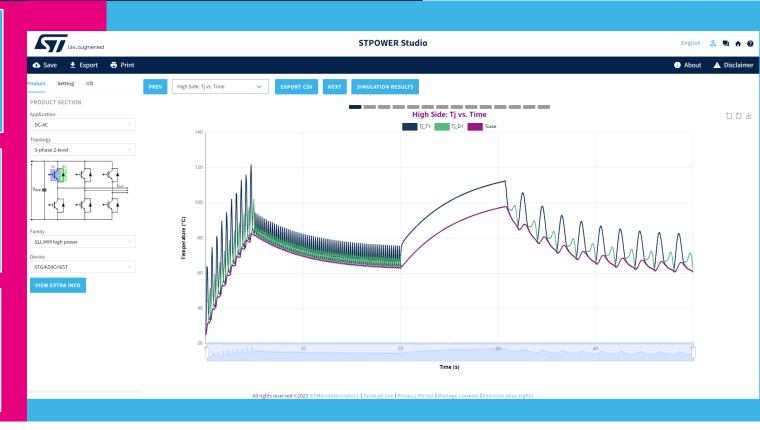
Comprehensive analysis:

- Multistep mission profile
- Several thermal setup options
- Deep analysis of junction temperatures and power loss
- Very fast computational calculation



High versatility:

- Multilingual interface (English, Chinese, Japanese)
- Link with product folder and datasheet
- Project save and export options
- Output report generation





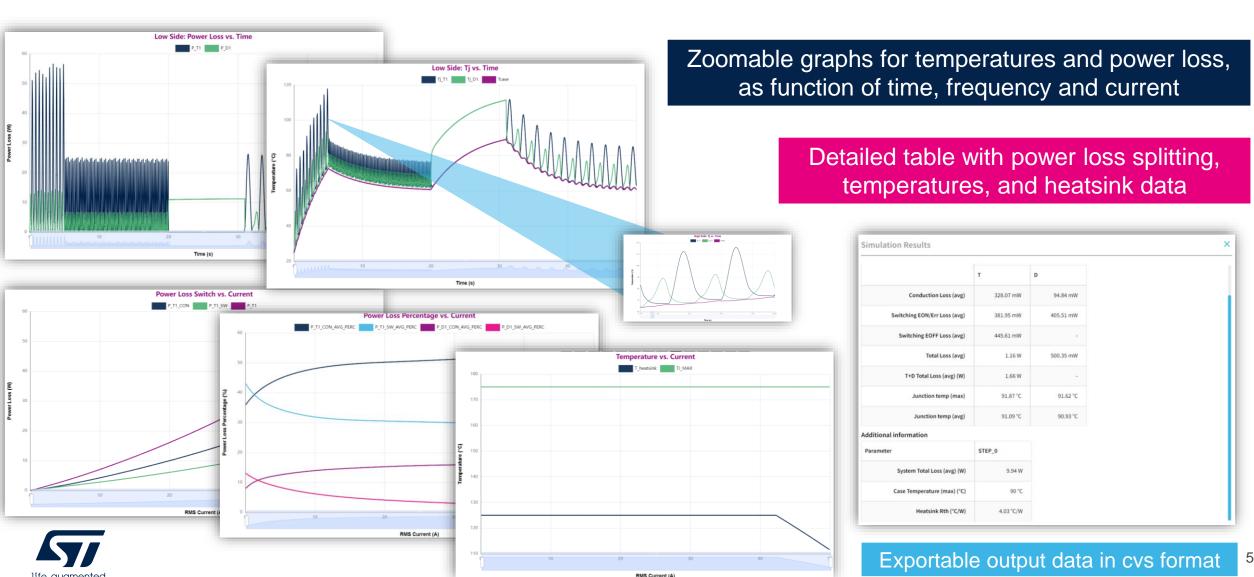


Graphical user interface



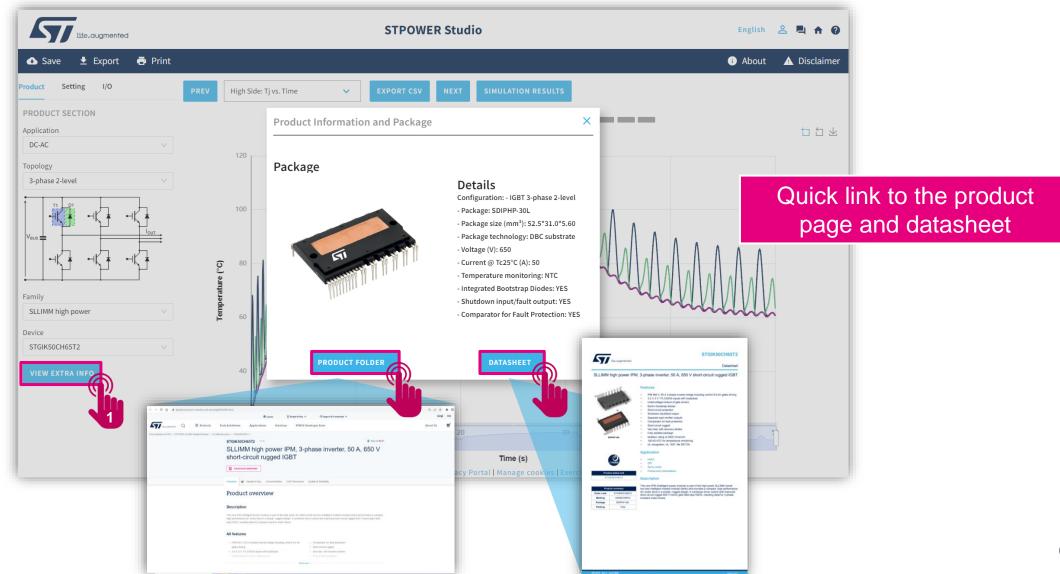


Output data





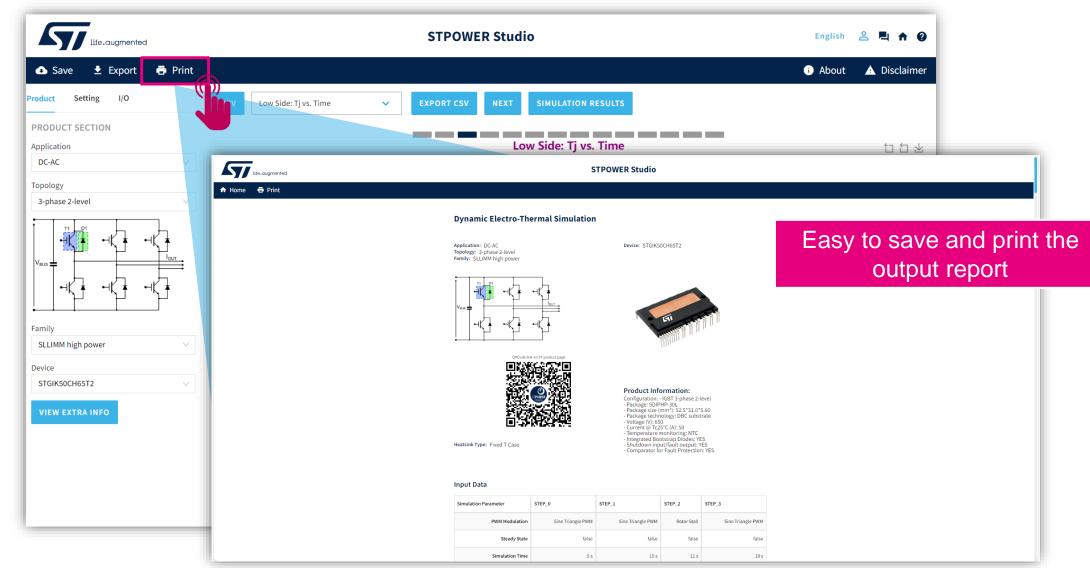
Connectivity







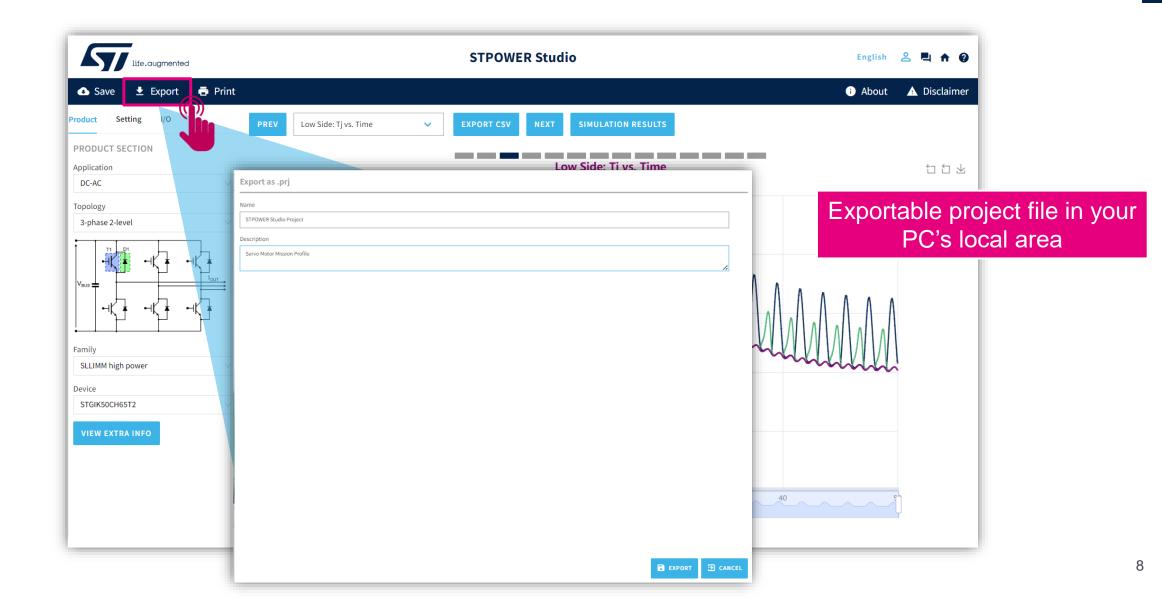
Printable output report







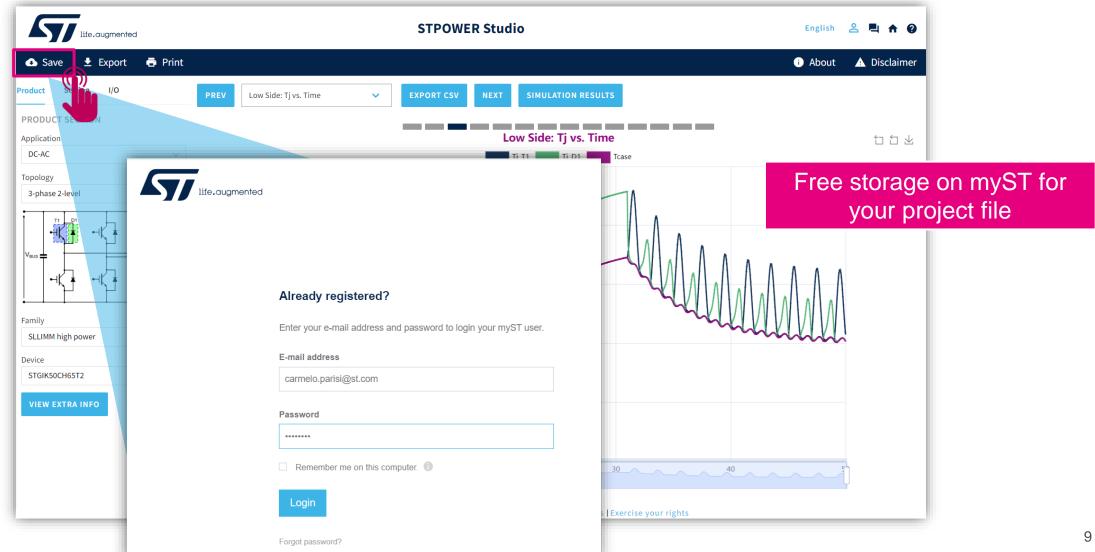
Exportable project







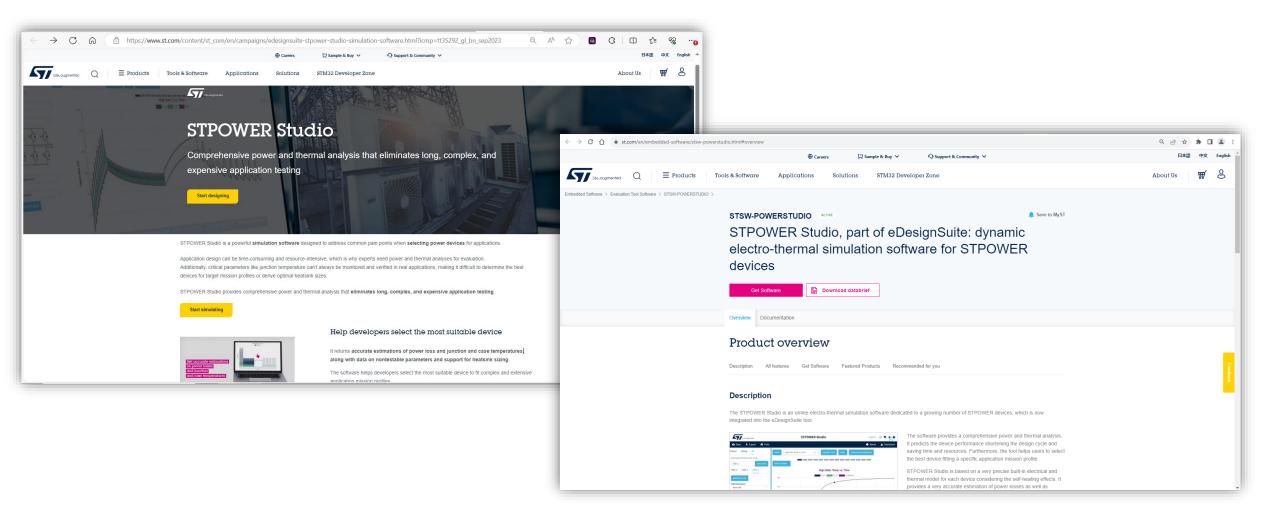
Free storage on myST







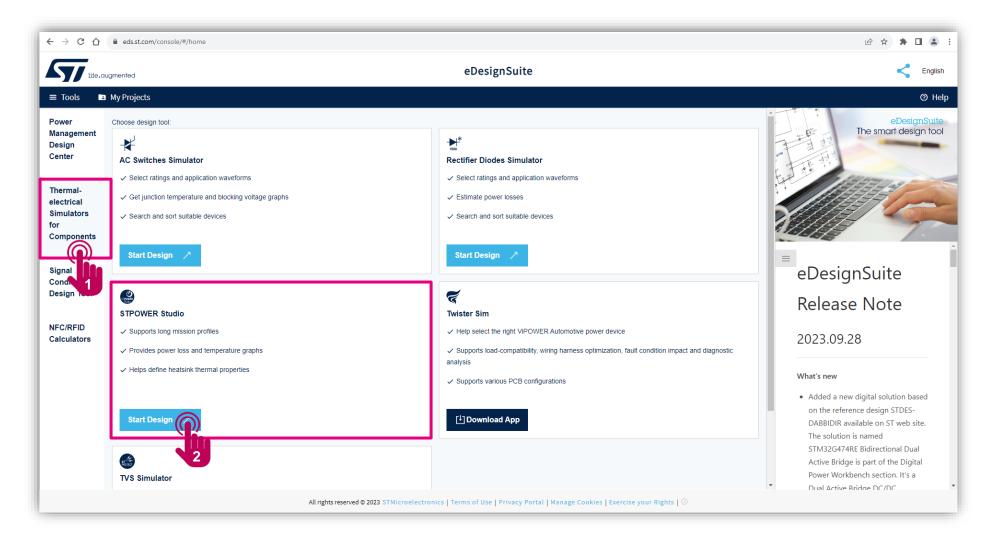
Dedicated web pages







Part of eDesignSuite





Our technology starts with You



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